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**Quality and technical requirements for metal packages used for
integrated circuits**

集成电路金属封装外壳质量技术要求

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Foreword

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Technical requirements for the quality of integrated circuit metal packaging casings

1 Scope

This document specifies the materials, plating, design and structure, electrical characteristics, appearance quality and environmental adaptability of integrated circuit metal packaging casings:

technical requirements and inspection methods:

This document applies to the development, production, delivery and use of integrated circuit metal packaging casings (hereinafter referred to as "casings"):

2 Normative reference documents

GB/T 4937

GB/T 4937

GB/T 4937

GB/T 4937

GB/T 4937

GB/T 16526

GB/T 19248

IEC 60749

IEC 60749

IEC 60749

3 Terms and definitions

The following terms and definitions apply to this document: 3:1 wall sidewall The inner surface of the housing that forms the sealed cavity:

NOTE: Contains and protects product circuitry with connections extending to leads inside the enclosure: 3:2 base The main support area at the bottom of the enclosure: